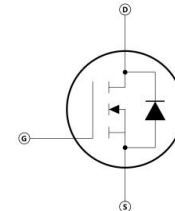
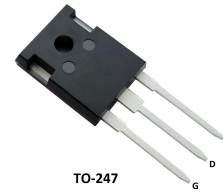


**Features**

- 100% avalanche tested
- Fast Intrinsic Diode
- Gate charge minimized
- Very low intrinsic capacitances
- High speed switching


**Applications**

- High Voltage Power Supplies
- PV Inverter
- Switching applications

**Electrical ratings**

Absolute maximum ratings			
Parameter	Symbol	Value	Unit
Drain-source voltage ( $V_{GS} = 0$ )	$V_{DS}$	2500	V
Gate- source voltage	$V_{GS}$	$\pm 30$	
Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	$I_D$	1	A
Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$		0.6	
Drain current (pulsed)	$I_{DM}$	6	
Total dissipation at $T_C = 25\text{ }^\circ\text{C}$	$P_D$	83	W
Single pulse avalanche energy (starting $T_J = 25\text{ }^\circ\text{C}$ , $I_D = I_{AR}$ , $V_{DD} = 50\text{ V}$ )	EAS	800	mJ
Operating junction temperature	$T_J$	-55 ~ 150	$^\circ\text{C}$
Storage temperature	$T_{stg}$		
Maximum lead temperature for soldering purpose	$T_L$	300	$^\circ\text{C}$
Mounting Torque	Md	1.13	N • m
Weight	G	6	g

**Electrical Characteristics** ( $T_{vj} = 25\text{ }^\circ\text{C}$  unless otherwise specified)

On /off states						
Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 250\text{ }\mu\text{A}$ , $V_{GS} = 0$	2500			V
Zero gate voltage drain current ( $V_{GS} = 0$ )	$I_{DSS}$	$V_{DS} = \text{Max rating}$ $V_{DS} = \text{Max rating}$ , $T_C = 125\text{ }^\circ\text{C}$			100 1000	$\mu\text{A}$
Gate-body leakage current ( $V_{DS} = 0$ )	$I_{GSS}$	$V_{GS} = \pm 30\text{ V}$			$\pm 200$	nA

Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250 \mu A$	4.5		6.5	V
Static drain-source on resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 50mA$	-	30	50	$\Omega$

Dynamic						
Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Forward transconductance	$g_{fs}$	$V_{DS} = 15 V, I_D = 0.5A$	88	145		mS
Input capacitance	$C_{iss}$	$V_{DS}=25V, f=1MHz, V_{GS}=0$		116		pF
Output capacitance	$C_{oss}$			8		
Reverse transfer capacitance	$C_{rss}$			3		
Total gate charge	$Q_g$	$V_{DD}=1250V, I_D=0.5mA$ $V_{GS}=10V$		7.4		nC
Gate-source charge	$Q_{gs}$			0.7		
Gate-drain charge	$Q_{gd}$			5.3		
Switching times						
Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Turn-on delay time	$t_{d(on)}$	<b>Resistive load</b> $V_{DD} = 1250 V, I_D = 0.5A,$ $R_G = 4.7 \Omega, V_{GS} = 10 V$		19		ns
Rise time	$t_r$			19		
Turn-off-delay time	$t_{d(off)}$			32		
Fall time	$t_f$			33		
Source drain diode						
Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Source-drain current	$I_{SD}$				1	A
Source-drain current (pulsed)	$I_{SDM}$				4	
Forward on voltage	$V_{SD}$	$I_{SD} = 1A, V_{GS} = 0$			1.3	V
Reverse recovery time	$t_{rr}$	$I_{SD} = 1A, di/dt=50A/\mu s$ $V_{DD} = 100 V$		1500		ns
Reverse recovery charge	$Q_{rr}$			9		$\mu C$
Reverse recovery current	$I_{RRM}$			0.3		A
Reverse recovery time	$t_{rr}$	$S_D=15A, di/dt=100A/\mu s$ $V_{DD}= 60V T_J=150^\circ C$		1300		ns
Reverse recovery charge	$Q_{rr}$			8.5		$\mu C$
Reverse recovery current	$I_{RRM}$			0.25		A

Thermal data			
Parameter	Symbol	Value	Unit
Thermal resistance junction-case max	$R_{thj-case}$	1.5	$W/^{\circ}C$
Thermal resistance junction-ambient max	$R_{thj-amb}$	50	

### Electrical characteristics

Fig. 1. Output Characteristics @  $T_J = 25^{\circ}C$

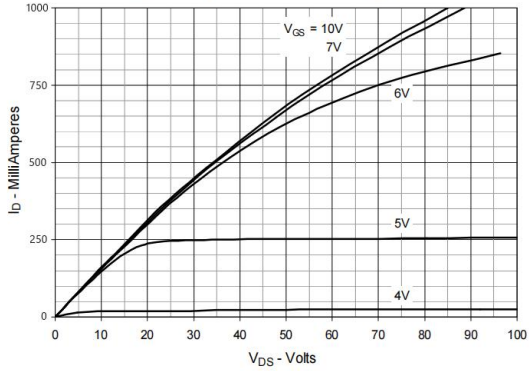


Fig. 2. Extended Output Characteristics @  $T_J = 25^{\circ}C$

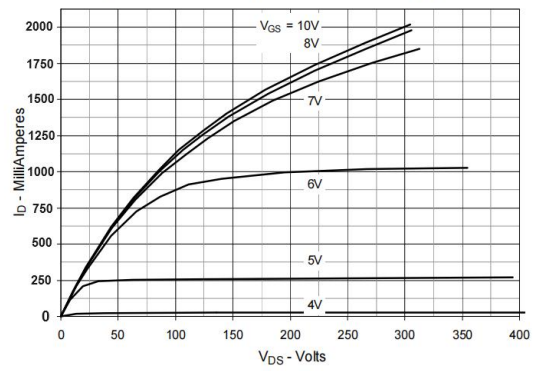


Fig. 3. Output Characteristics @  $T_J = 125^{\circ}C$

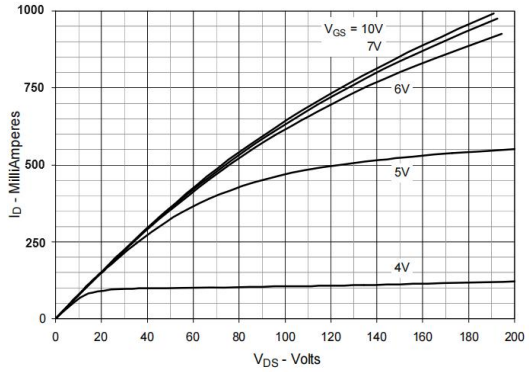


Fig. 4.  $R_{DS(on)}$  Normalized to  $I_D = 100mA$  Value vs. Junction Temperature

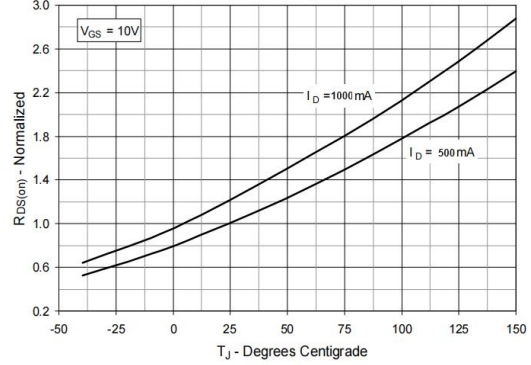


Fig. 5.  $R_{DS(on)}$  Normalized to  $I_D = 100mA$  Value vs. Drain Current

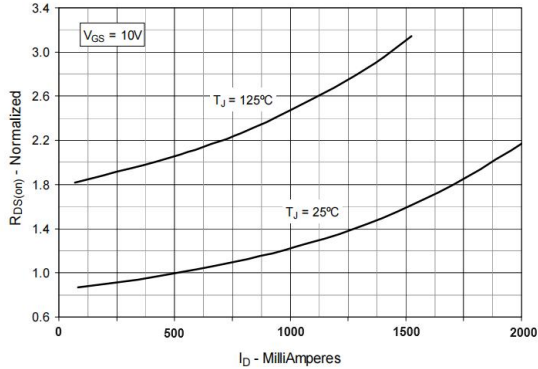
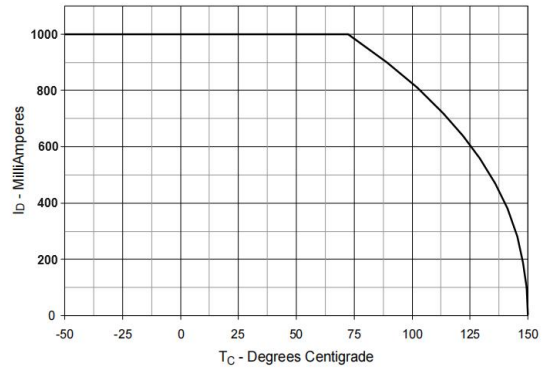
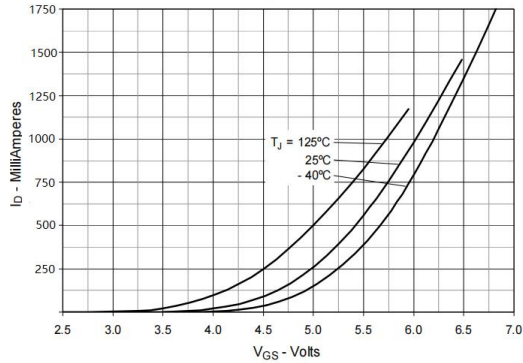


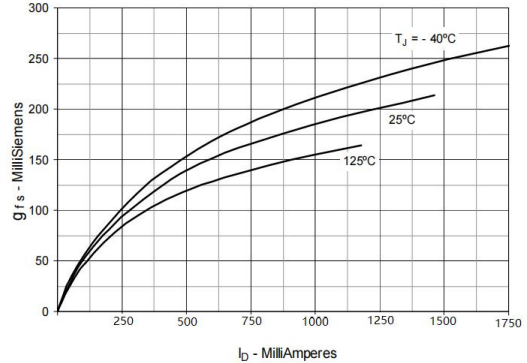
Fig. 6. Maximum Drain Current vs. Case Temperature



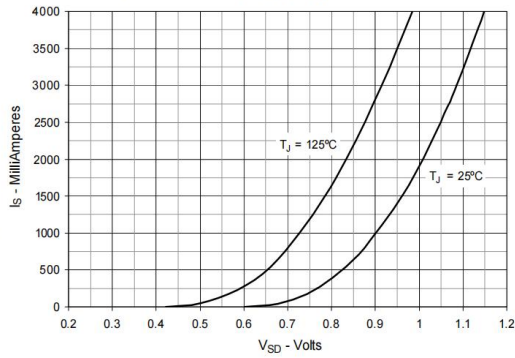
**Fig. 7. Input Admittance**



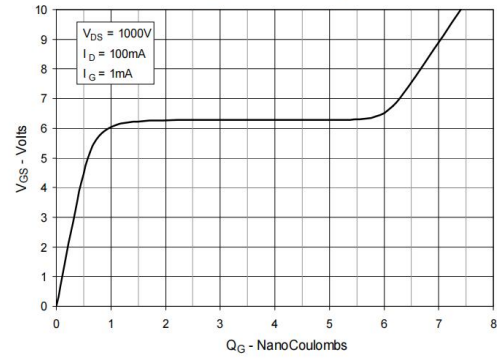
**Fig. 8. Transconductance**



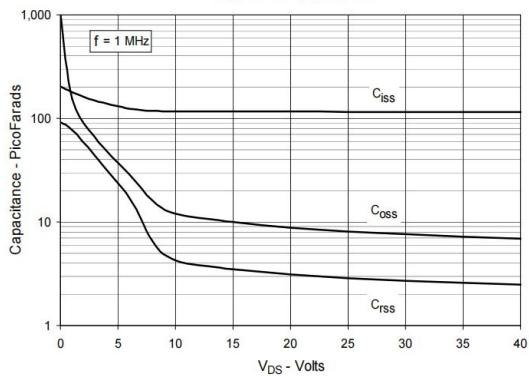
**Fig. 9. Forward Voltage Drop of Intrinsic Diode**



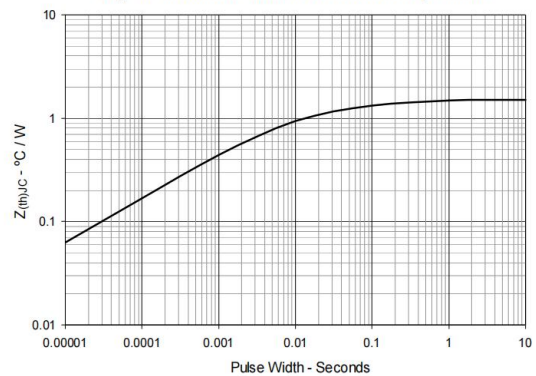
**Fig. 10. Gate Charge**



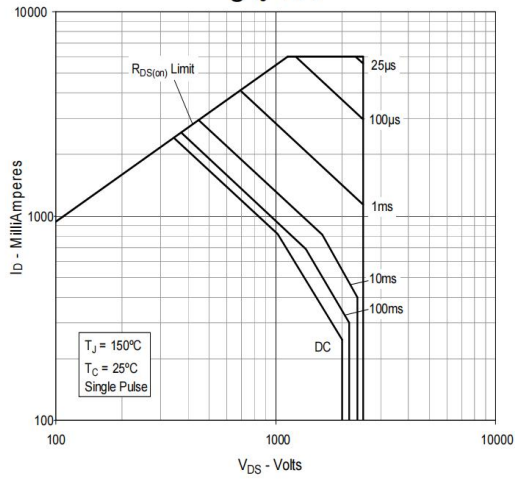
**Fig. 11. Capacitance**



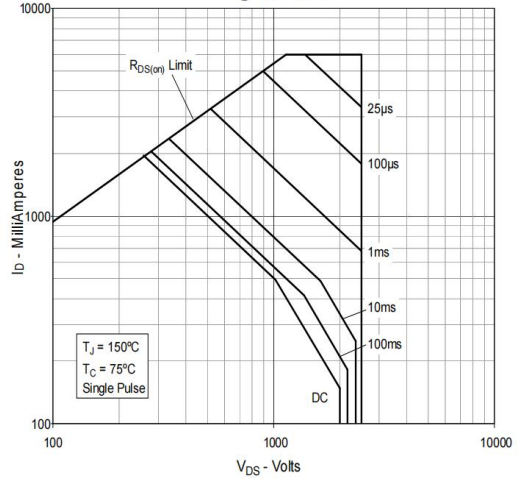
**Fig. 12. Maximum Transient Thermal Impedance**



**Fig. 13. Forward-Bias Safe Operating Area**  
@  $T_C = 25^\circ\text{C}$



**Fig. 14. Forward-Bias Safe Operating Area**  
@  $T_C = 75^\circ\text{C}$



### Package outline dimension

